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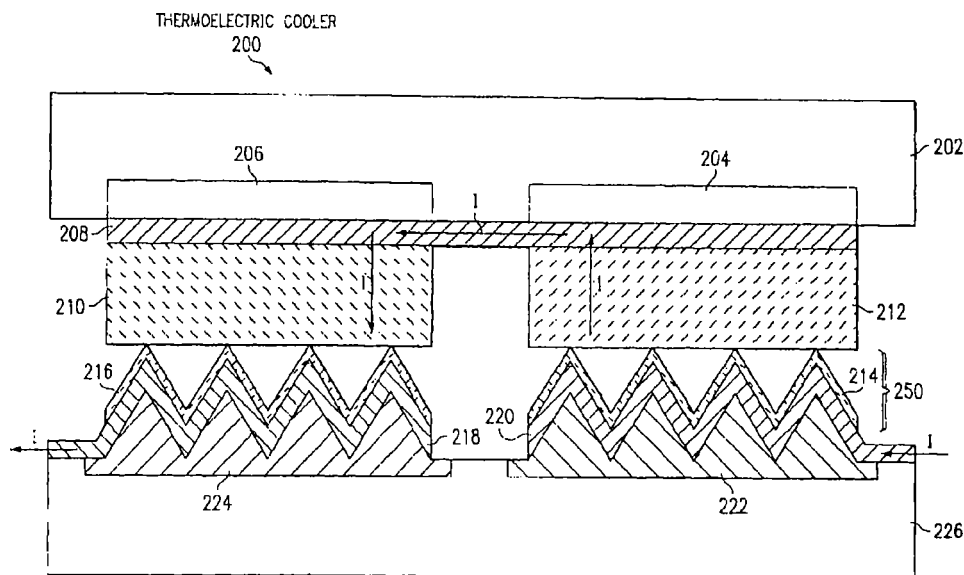
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(54) Title: ENHANCED INTERFACE THERMOELECTRIC COOLERS



(57) Abstract: A thermoelectric device with improved efficiency is provided. In one embodiment, the thermoelectric device includes a first thermoelement and a second thermoelement electrically coupled to the first thermoelement. An array of first tips are in close physical proximity to, but not necessarily in physical contact with, the first thermoelement at a first set of discrete points. An array of second tips are in close physical proximity to, but not necessarily in physical contact with, the second thermoelement at a second set of discrete points. The arrays of first and second tips are constructed from metal, thus reducing parasitic resistances.

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